



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20170614000
Datasheet for DAC081C081, DAC081C085
Information Only**

Date: June 27, 2017
To: PREMIER FARNELL PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

**Information Only
Attachments**

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
DAC081C081CIMK/NOPB	null
DAC081C085CIMM/NOPB	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20170614000	PCN Date:	June 27, 2017
Title:	Datasheet for DAC081C081, DAC081C085		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



DAC081C081, DAC081C085

SNAS449F – FEBRUARY 2008 – REVISED MAY 2017

Changes from Revision E (January 2016) to Revision F

Page

- Added column to Table 1. 21

The datasheet number will be changing.

Device Family	Change From:	Change To:
DAC081C081, DAC081C085	SNAS449E	SNAS449F

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/DAC081C081>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

DAC081C081CIMK/NOPB	DAC081C081CIMKX/NOPB	DAC081C081CISD/NOPB	DAC081C081CISDX/NOPB
DAC081C085CIMM/NOPB	DAC081C085CIMMX/NOPB		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com